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No. 08/046,720, filed April 16, 1993, now U.S. Patent No. 5,463,459, which is a continuation-in-part of U.S. application Serial No. 07/679,317, filed April 2, 1991, now U.S. Patent No. 5,233,191 and U.S. application Serial No. 07/778,363, filed October 17, 1991, now U.S. Patent No. 5,274,434, U.S. application Serial No. 07/778,363 being a continuation-in-part application of U.S. application Serial No. 07/679,317.

IN THE CLAIMS:

Please add the following new claims:

--12. A semiconductor processing method, comprising the steps of:

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detecting foreign particle defects on a substrate by a foreign particle detection means attached to at least one processing apparatus which is a component of a semiconductor fabricating system; and

determining the foreign particle generating condition of at least one of the at least one processing apparatus.

13. A semiconductor processing method according to claim 12, wherein the foreign particle on the substrate is detected during a transfer of the substrate by a transfer unit.

14. A semiconductor processing method according to claim 12, wherein an information of the foreign particle defects is